

3.2mmx3.6mm FULL-COLOR SURFACE MOUNT LED LAMP



ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: APF3236SURKVGAPBA

Hyper Red Green Blue

Features

- 3.2mmx3.6mm SMT LED, 1.1mm thickness.
- Low power consumption.
- One red, one green and one blue chips in one package.
- Can produce any color in visible spectrum, including white light.
- Package: 1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

The Green source color devices are made with InGaN on G-SiC Light Emitting Diode.

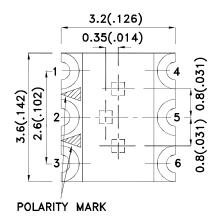
The Blue source color devices are made with InGaN on SiC Light Emitting Diode.

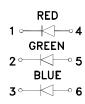
Static electricity and surge damage the LEDS.

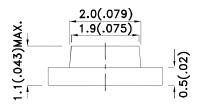
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

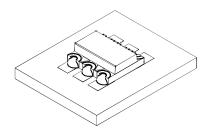
All devices, equipment and machinery must be electrically grounded.

Package Dimensions









- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
APF3236SURKVGAPBA	Hyper Red (AlGaInP)		70	220	120°
	Green (InGaN)	WATER CLEAR	50	150	
	Blue (InGaN)		18	60	

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green Blue	650 520 468		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red Green Blue	630 525 470		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green Blue	28 35 21		nm	IF=20mA
С	Capacitance	Hyper Red Green Blue	35 100 100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green Blue	1.95 3.2 3.2	2.5 4 4	V	IF=20mA
lr	Reverse Current	Hyper Red Green Blue		10 10 10	uA	VR=5V

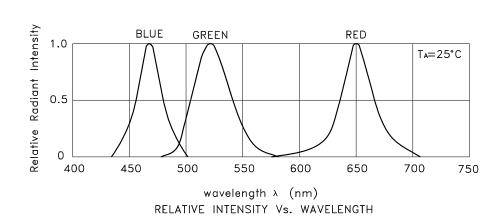
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

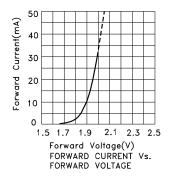
Parameter	Hyper Red	Green	Blue	Units		
Power dissipation	75	120	120	mW		
DC Forward Current	30	30	30	mA		
Peak Forward Current [1]	185	100	100	mA		
Reverse Voltage	5 V					
Operating Temperature	-40°C To +85°C					
Storage Temperature	-40°C To +85°C					

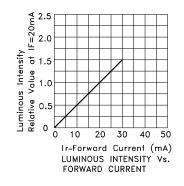
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

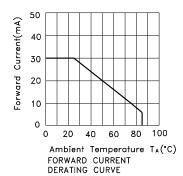
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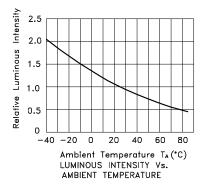


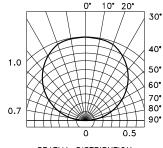
APF3236SURKVGAPBA Hyper Red









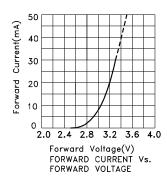


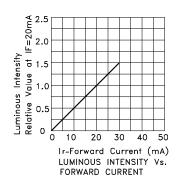
SPATIAL DISTRIBUTION

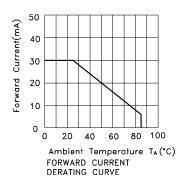
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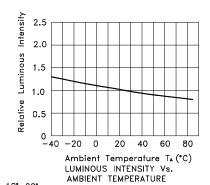
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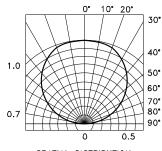
Green









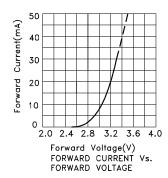


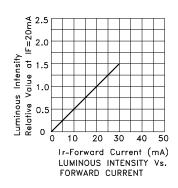
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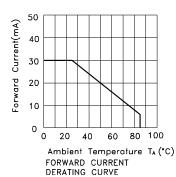
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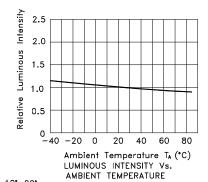
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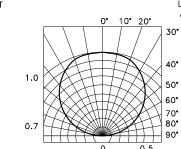
Blue











SPATIAL DISTRIBUTION

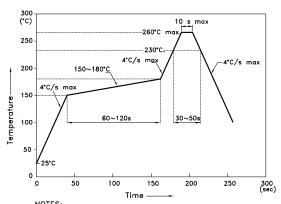
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



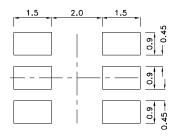
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

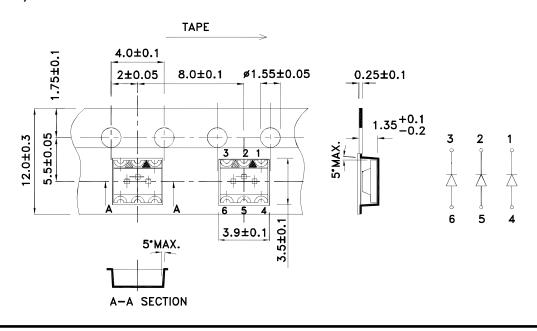
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. to high temperature.

 3.Number of reflow process shall be 2 times or less.

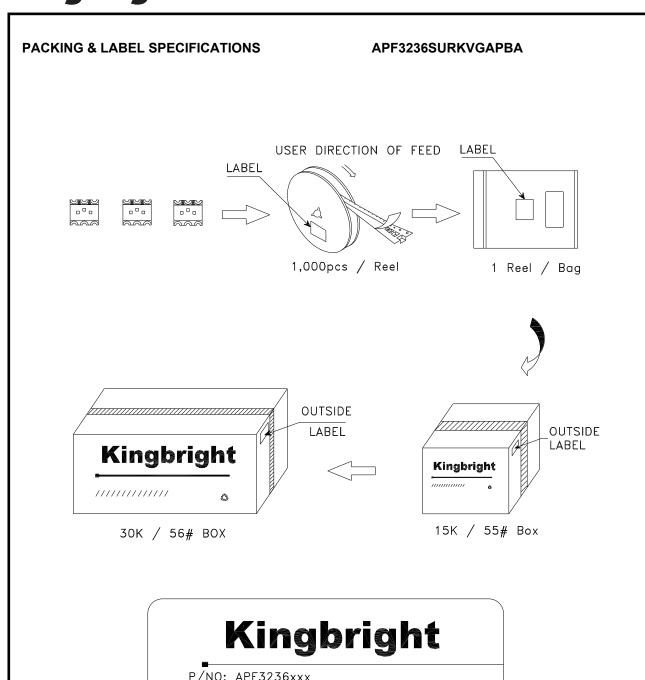
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)



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